PCN Number:	er: 20170829000					PCN Date:		Date:	Aug 30, 2017		
Title: Qualify New Assembly Material set for Selected Device(s)											
Customer Contact:	<u>Manager</u>		Phon	e:	+1(214)4	480-6037 Dept:			Quality Services		
Proposed 1 st Ship Date:		Nov 30, 2017				Estimated Sample Availability:			Date provided at sample request		
Change Type:											
Assembly Site			Design						Wafer Bump Site		
Assembly Process			Data Sheet					$\underline{\sqcup}$	Wafer Bump Material		
Assembly Materials			Part number change Wafer Bump Pro								
Mechanical Specification			Test Site				Щ	Wafer F			
Packing/Shipping/	Label	ing	Test Process				닏		ab Materials		
							Ш	water F	ab Process		
				PCN	ре	tails					
Description of Chang											
Texas Instruments is p											
devices listed in "Produ			sec	tion belo	w. I	Devices w	ill re	ema	ain in curre	ent assembly facility	
and piece part changes	as i	ollows:									
Material		<u> </u>	ırr	ont		Propos	ad a		7		
Mount compour			Current 4207768			4207123					
Lead finish			Standard NiPdAu			Roughened NiPdAu					
Reason for Change:		Jeana	<u> </u>	Till arta		agriciica	• • • • • • • • • • • • • • • • • • •	···			
Continuity of supply.											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
None.											
Anticipated impact on Material Declaration											
□ No Impact to the	Material Declarations or Product Content reports are driven from										
Material		production data and will be available following the production									
Declaration		release. Upon production release the revised reports can be									
		obtained from the <u>TI Eco-Info website</u> . There is no impact to the material meeting current regulatory compliance requirements									
			with this PCN change.								
with this references.											
Changes to product identification resulting from this PCN:											
None.											
Product Affected:											
DRV2700RGPR DRV2700RGPT											

Qualification Report

DRV2700RGP with CRM1076NS and roughened LF at MSL2-260C

Approve Date 10-Aug-2017

Product Attributes

Attributes	Qual Device: DRV2700RGP	QBS Package Reference: SH6966ACC0RGCRG4	QBS Package Reference: SNA1038ARGC
Assembly Site	CLARK-AT	CLARK-AT	UL 94 V-0
Package Family	QFN	QFN	RGC
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	HIJI	MIHO8	RFAB
Wafer Fab Process	LBCSOI	LBC7	LBC7

⁻ QBS: Qual By Similarity

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Data Displayed as: Number of lots / Total sample size / Total failed					
Туре	Test Name / Condition	Duration	Qual Device: DRV2700RGP	QBS Package Reference: SH6966ACC0RGCRG4	QBS Package Reference: SNA1038ARGC
AC	Autoclave 121C	96 Hours	1/77/0	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	1/3/0	-	-
HBM	ESD - HBM	4000 V	1/3/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	3/231/0
SD	Solderability	8 Hours Steam Age	-	3/66/0	-
тс	Temperature Cycle, -65/150C	500 Cycles	1/77/0	3/231/0	-
TS	Thermal Shock - 65/150C	500 Cycles	-	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	3/230/0
WBP	Bond Pull	Wires	1/76/0	3/228/0	-
WBS	Wire Bond Shear	Wires	1/76/0	3/228/0	-

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

⁻ Qual Device DRV2700RGP is qualified at LEVEL2-260C

⁻ The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

⁻ The following are equivalent HTSL options based on an activation energy of $0.7 \mathrm{eV}$: $150 \mathrm{C}/1 \mathrm{k}$ Hours, and $170 \mathrm{C}/420$ Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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